

EN: This Datasheet is presented by the manufacturer.

Please visit our website for pricing and availability at www.hestore.hu.

- 8 A Continuous On-State Current
- 80 A Surge-Current
- Glass Passivated Wafer
- 400 V to 800 V Off-State Voltage
- Max I_{GT} of 20 mA

Pin 2 is in electrical contact with the mounting base.

MDC1ACA

absolute maximum ratings over operating case temperature (unless otherwise noted)

RATING	SYMBOL	VALUE	UNIT		
	TIC116D		400		
Repetitive peak off-state voltage (see Note 1)	TIC116M	\/	600	V	
	TIC116S	V_{DRM}	700	٧	
	TIC116N		800		
	TIC116D		400		
Repetitive peak reverse voltage	TIC116M	\/	600	V	
	TIC116S	V_{RRM}	700		
	TIC116N		800		
Continuous on-state current at (or below) 80°C case temperature (see Note 2)	I _{T(RMS)}	8	Α		
Average on-state current (180° conduction angle) at (or below) 80°C case temperature of the conduction angle of the conduction and the conductio	L	5	Α		
(see Note 3)	I _{T(AV)}	3	^		
Surge on-state current (see Note 4)			80	Α	
Peak positive gate current (pulse width ≤ 300 μs)	I _{GM}	3	Α		
Peak gate power dissipation (pulse width ≤ 300 μs)	P_{GM}	5	W		
Average gate power dissipation (see Note 5)	$P_{G(AV)}$	1	W		
Operating case temperature range	T _C	-40 to +110	°C		
Storage temperature range	T _{stg}	-40 to +125	°C		
Lead temperature 1.6 mm from case for 10 seconds	T _L	230	°C		

NOTES: 1. These values apply when the gate-cathode resistance R_{GK} = 1 $k\Omega$

- 2. These values apply for continuous dc operation with resistive load. Above 80°C derate linearly to zero at 110°C.
- 3. This value may be applied continuously under single phase 50 Hz half-sine-wave operation with resistive load. Above 80°C derate linearly to zero at 110°C.
- 4. This value applies for one 50 Hz half-sine-wave when the device is operating at (or below) the rated value of peak reverse voltage and on-state current. Surge may be repeated after the device has returned to original thermal equilibrium.
- 5. This value applies for a maximum averaging time of 20 ms.



TIC116 SERIES SILICON CONTROLLED RECTIFIERS

APRIL 1971 - REVISED MARCH 1997

electrical characteristics at 25°C case temperature (unless otherwise noted)

PARAMETER			TEST CONDITIONS			TYP	MAX	UNIT
I _{DRM}	Repetitive peak off-state current	V _D = rated V _{DRM}	R _{GK} = 1 kΩ	T _C = 110°C			2	mA
I _{RRM}	Repetitive peak reverse current	V _R = rated V _{RRM}	I _G = 0	T _C = 110°C			2	mA
I _{GT}	Gate trigger current	V _{AA} = 6 V	$R_L = 100 \Omega$	t _{p(g)} ≥ 20 μs		5	20	mA
V _{GT} Gate trigger volta		$V_{AA} = 6 V$ $t_{p(g)} \ge 20 \mu s$	$R_L = 100 \Omega$ $R_{GK} = 1 k\Omega$	T _C = - 40°C			2.5	
	Gate trigger voltage	$V_{AA} = 6 \text{ V}$ $t_{p(g)} \ge 20 \mu\text{s}$	$R_L = 100 \Omega$ $R_{GK} = 1 k\Omega$			0.8	1.5	٧
		$V_{AA} = 6 \text{ V}$ $t_{p(g)} \ge 20 \mu\text{s}$	$R_L = 100 \Omega$ $R_{GK} = 1 k\Omega$	T _C = 110°C	0.2			
I _H	Holding current	$V_{AA} = 6 \text{ V}$ Initiating $I_T = 100 \text{ mA}$	$R_{GK} = 1 k\Omega$	T _C = - 40°C			70	mA
		$V_{AA} = 6 \text{ V}$ Initiating $I_T = 100 \text{ mA}$	$R_{GK} = 1 k\Omega$				40	III/A
V _{TM}	Peak on-state voltage	I _{TM} = 8 A	(see Note 6)				1.7	٧
dv/dt	Critical rate of rise of off-state voltage	V_D = rated V_D	I _G = 0	T _C = 110°C		100		V/µs

NOTE 6: This parameter must be measured using pulse techniques, $t_p = 300 \mu s$, duty cycle $\leq 2 \%$. Voltage sensing-contacts, separate from the current carrying contacts, are located within 3.2 mm from the device body.

thermal characteristics

PARAMETER			TYP	MAX	UNIT
$R_{\theta JC}$	Junction to case thermal resistance			3	°C/W
$R_{\theta JA}$	Junction to free air thermal resistance			62.5	°C/W

resistive-load-switching characteristics at 25°C case temperature

	PARAMETER	TEST CONDITIONS			MIN	TYP	MAX	UNIT
t _{gt}	Gate-controlled turn-on time	I _T = 5 A	I _G = 200 mA	See Figure 1		0.8		μs
t _q	Circuit-commutated turn-off time	I _T = 5 A	I _{RM} = 10 A	See Figure 2		11		μs

PARAMETER MEASUREMENT INFORMATION

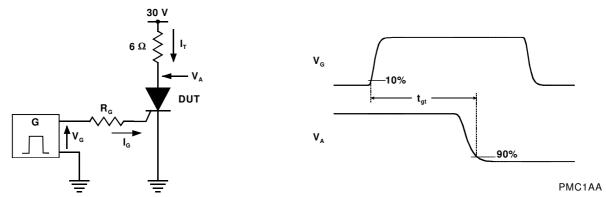
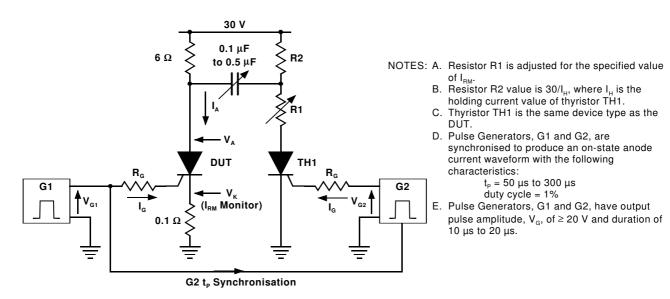


Figure 1. Gate-controlled turn-on time



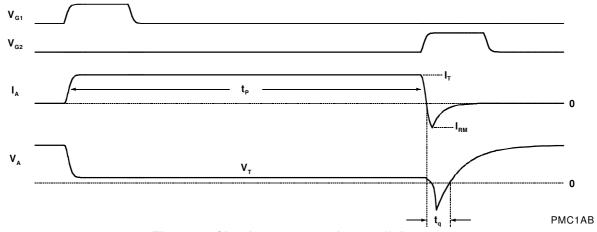
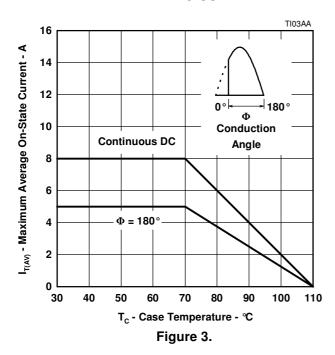


Figure 2. Circuit-commutated turn-off time

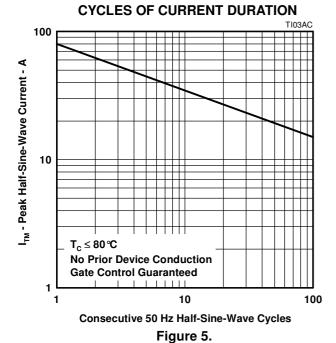


TYPICAL CHARACTERISTICS

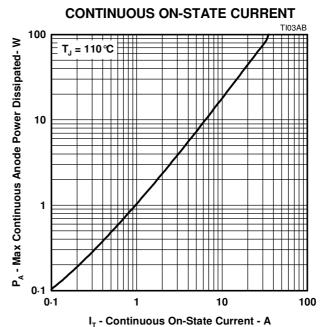
AVERAGE ON-STATE CURRENT DERATING CURVE



SURGE ON-STATE CURRENT vs

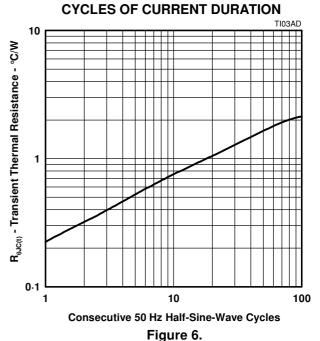


MAX CONTINUOUS ANODE POWER DISSIPATED vs



TRANSIENT THERMAL RESISTANCE vs

Figure 4.



PRODUCT INFORMATION

TYPICAL CHARACTERISTICS

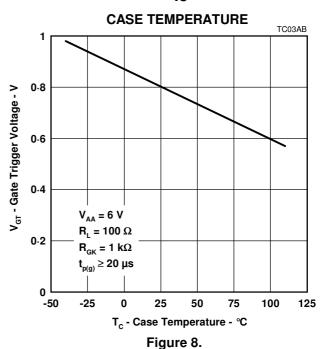
GATE TRIGGER CURRENT vs

GATE FORWARD VOLTAGE vs

Figure 7.

GATE FORWARD CURRENT TC03AC 10 $I_A = 0$ T_C = 25 ℃ $t_{\rm p} = 300 \; \mu s$ V_{GF} - Gate Forward Voltage - V Duty Cycle ≤ 2 % 1 0.1 0.01 10 100 1000 I_{GF} - Gate Forward Current - mA Figure 9.

GATE TRIGGER VOLTAGE

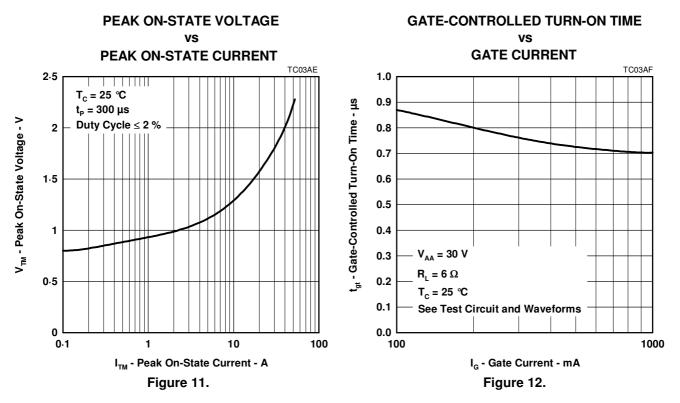


HOLDING CURRENT vs

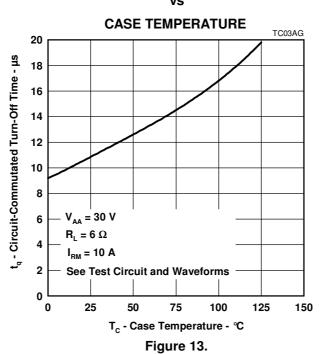
CASE TEMPERATURE TC03AD V_{AA} = 6 V R_{GK} = 1 k Ω Initiating I_T = 100 mA -50 -25 0 25 50 75 100 125 T_C - Case Temperature - $^{\circ}$ C Figure 10.



TYPICAL CHARACTERISTICS



CIRCUIT-COMMUTATED TURN-OFF TIME vs

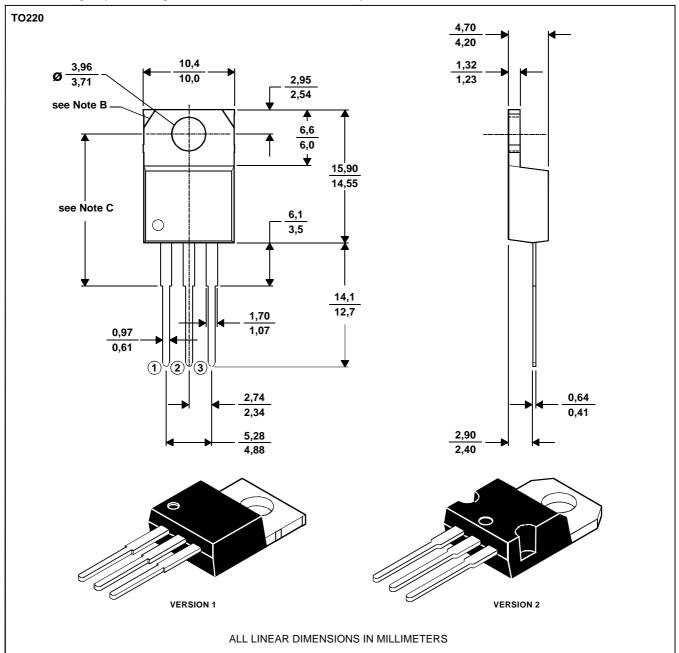


MECHANICAL DATA

TO-220

3-pin plastic flange-mount package

This single-in-line package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. Leads require no additional cleaning or processing when used in soldered assembly.



NOTES: A. The centre pin is in electrical contact with the mounting tab.

B. Mounting tab corner profile according to package version.

C. Typical fixing hole centre stand off height according to package version. Version 1, 18.0 mm. Version 2, 17.6 mm. MDXXBE



TIC116 SERIES SILICON CONTROLLED RECTIFIERS

APRIL 1971 - REVISED MARCH 1997

IMPORTANT NOTICE

Power Innovations Limited (PI) reserves the right to make changes to its products or to discontinue any semiconductor product or service without notice, and advises its customers to verify, before placing orders, that the information being relied on is current.

PI warrants performance of its semiconductor products to the specifications applicable at the time of sale in accordance with PI's standard warranty. Testing and other quality control techniques are utilized to the extent PI deems necessary to support this warranty. Specific testing of all parameters of each device is not necessarily performed, except as mandated by government requirements.

PI accepts no liability for applications assistance, customer product design, software performance, or infringement of patents or services described herein. Nor is any license, either express or implied, granted under any patent right, copyright, design right, or other intellectual property right of PI covering or relating to any combination, machine, or process in which such semiconductor products or services might be or are used.

PI SEMICONDUCTOR PRODUCTS ARE NOT DESIGNED, INTENDED, AUTHORIZED, OR WARRANTED TO BE SUITABLE FOR USE IN LIFE-SUPPORT APPLICATIONS, DEVICES OR SYSTEMS.

Copyright © 1997, Power Innovations Limited